New Product Introduction May 2026

BATTERY MANAGEMENT ICS

16ch BMS Balancing and Monitoring IC TLE9016DQK

MICROCONTROLLER

TRAVEO™ T2G CYT6BJ series MCU for body electrics

POWER

CIPOS™ Prime 1200 V Automotive CoolSiC™ Power Module

OPTIREG™ PMIC TLE9744QK Application Specific PMIC for traction inverter

EiceDRIVER™ 1EDI304xAS isolated gate driver ICs for EV

FF2000R17T2P8 / FF1400R17T2P8 1700 V, 2000 A/1400 A half-bridge IGBT module in XHP™2 package

OptiMOS™ 5 30 V and OptiMOS™ 6 40 V portfolio extension in Source-Down PQFN 3.3x3.3 with excellent price-performance ratio

OptiMOS™ 7 40 V motor-drives optimized power MOSFETs

OptiMOS™ 80 V and 100 V top-side cooled SSO10T for 48 V motor drive, DC-DC converters and exterior LED lighting applications

OptiMOS™ 7 40 V in SSO4G 5x6 package

OptiMOS™ 8 ISC019N10NM8SC n-channel power MOSFET 100 V in SuperSO8 DSC package with dual-side cooling (DSC)

EconoPACK™ 3 with IGBT7 for MV drives and motor control

SENSOR TECHNOLOGY

XENSIV™ TLI55950 amplified linear TMR position sensor

XENSIV™ TLI55910 linear TMR position sensor

UNIVERSAL SERIAL BUS

EZ-PD™ CCG7S for automotive USB-C applications

EVALUATION BOARDS

REF_10KW_3LBUCK_SiC400 3-level flying capacitor buck with CoolSiC™ MOSFET 400 V G2

16ch BMS Balancing and Monitoring IC TLE9016DQK

TLE9016DQK is a multi-channel battery monitoring and balancing IC crafted for Li-Ion battery packs in automotive (MHEV, HEV, PHEV, BEV), industrial (ESS, data centers, robotics), and consumer applications (e-bike BMS, home energy storage). It handles cell voltage and temperature measurement, cell balancing and isolated communication to the main battery controller. Moreover, it includes essential diagnostic tools for safety assurance.

Features

- Balancing and monitoring for up to 16 cells in series
- Robust Infineon 120 V automotive technology supports harshest stress and noise conditions
- Dedicated 16-bit delta-sigma ADC per cell enabling synced and filtered measurements, including built-in digital filtering for a minimum of external components and reduced system cost
- Internal round robin cycle routine for automated safety checks and mechanisms
- Supporting up to ASIL D BMS safety applications
- Compatible with Infineon Complex Device Driver for AURIX^{TM} TC36x/37x/38x

Benefits

- Robustness: Infineon technology and device architecture allow for best performance under noise with minimum amount of external protection devices
- High accuracy voltage measurement: reliable and precise battery cell monitoring for highly accurate SoC and SoH
- Lowest system cost: high feature integration for a lean external BOM

Competitive advantage

- High precision and accuracy with parallel ADC architecture to maximize battery pack efficiency
- Highly robust 120 V automotive technology and lean IC design – based on decades of automotive experience – enable the leanest BOM around the BMS IC, resulting in lowest system cost
- Infineon’s superior quality is reflected in lowest return rates, which are industry’s benchmark
- In addition, there is a complementing fully configurable and ASIL-D Complex Device Driver available for convenient design-in, reducing development time

Target applications

- Battery Electric Vehicle (BEV)
- Mild Hybrid Electric Vehicle (MHEV)
- Hybrid Electric Vehicle (HEV)
- Plug-in Hybrid Electric Vehicle (PHEV)
- 12 V Li-Ion battery systems
- Energy Storage Systems (ESS)

Product collaterals / Online support

Product page

Product overview incl. datasheet link

OPN	SP Number	Package
TLE9016DQKXUMA1	SP005864101	PG-LQFP-64

Classification: Restricted document! The information presented is valid from May 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

TRAVEO™ T2G CYT6BJ series MCU for body electrics

Infineon's TRAVEO™ T2G CYT6BJ series MCUs offer exceptional capabilities for automotive body electronics, featuring robust processing power and reliable network connectivity built around the quad Arm® Cortex®-M7 architecture. This series is tailored for various automotive applications, including zone control, body domain control and infotainment. The CYT6BJ series boasts a 320 MHz frequency quad core and a 16 MB flash capacity.

Features

- Up to 320 MHz main core frequency
- 16 MB flash with dual bank for OTA
- Low power consumption, DeepSleep 50 uA (typ)
- Power voltage range from 2.7 V to 5.5 V
- eMMC and Serial Memory Interface
- ISO26262 ASIL-B support
- CyberSecurity ISO21434-compliance
- 10Base-T1s, up to 1G Ethernet MAC

Benefits

- Quad cores with up to 2700 DMIPS
- Supports domain control and connected gateway ECUs
- Best-in-class low power mode controller
- Extensive connectivity options
- Supports ASIL-B ISO26262 safety standards
- HSM compliant eVita full for future-proof security
- High-speed communication interfaces

Competitive advantage

- Robust network interface for gateway functions
  - Up to 2x 1G Ethernet, up to 10 CAN, up to 20 LIN with Cybersecurity
- Cybersecurity and Functional Safety for Body Zone Control
  - ISO 21434 and ISO 26262 compliant
- CYT6BJ expands support for 16 MB and 2 MB memory to support growing software codes and true FOTA

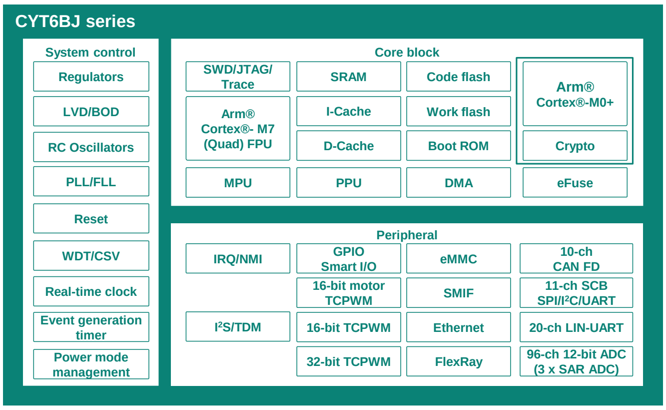
Target applications

- Automotive body electronics and power distribution
- Automotive body control module (BCM)
- Zone control unit

Product collaterals / Online support

Product page

Block diagram

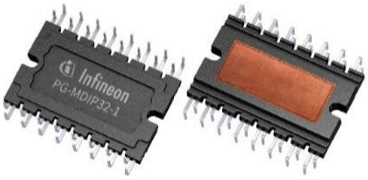


Product overview incl. datasheet link

OPN	SP Number	Package
CYT6BJCDHBQ0BZEGSXQLA1	SP006138088	PG-LFBGA-320

CIPOS™ Prime 1200 V Automotive CoolSiC™ Power Module

The CIPOS™ Prime 1200 V Automotive CoolSiC™ Power Module delivers best-in-class performance for xEV applications. Featuring automotive-grade CoolSiC™ MOSFETs in a fully isolated, compact molded package, it supports 6.6kW up to 44kW OBC and DC/DC topologies, AEC-Q101 and AQG324 qualified, it offers unmatched reliability, a Poka-Yoke zig-zag pin-out, and secured supply for next-generation electric vehicle systems.



Features

- 1200 V Automotive-grade CoolSiC™ MOSFET Molded Power Module optimized for xEV applications
- Fully isolated Dual In-line Package (DIP 44×28mm) in Full-Bridge and 3-Phase Bridge configurations
- 4-in-1 and 6-in-1 topologies with isolated DCB Aluminum Nitride (AlN) package
- Compact, industry-standard form factor with Poka-Yoke zig-zag pin-out design
- Automotive qualified per AEC-Q101 and AQG324
- Widest product portfolio — covers 11kW and 22kW OBC and DC/DC topologies with just 3 module variants
- Improved groove design over market-standard competitors

Benefits

- Best-in-class module solution — market-standard compatible with zig-zag pin-out for easy design-in
- Simplified procurement — cover 6.6 up to 44kW OBC and DC/DC topologies
- Poka-Yoke zig-zag pin-out — eliminates assembly errors and reduces production risk
- Drop-in replacement, with an improved groove design for enhanced robustness
- Best-in-class CoolSiC™ MOSFET — superior switching performance and efficiency

Competitive advantage

- Infineon's CIPOS™ Prime 1200 V module combines the broadest topology coverage in the market with a pin-compatible, drop-in replacement capability — reducing customer redesign effort while delivering superior CoolSiC™ MOSFET performance. The improved groove design and Poka-Yoke pin-out directly address key pain points in assembly quality and reliability, while AEC-Q101/AQG324 qualification and secured supply give automotive OEMs and Tier-1 suppliers the confidence to design in at scale

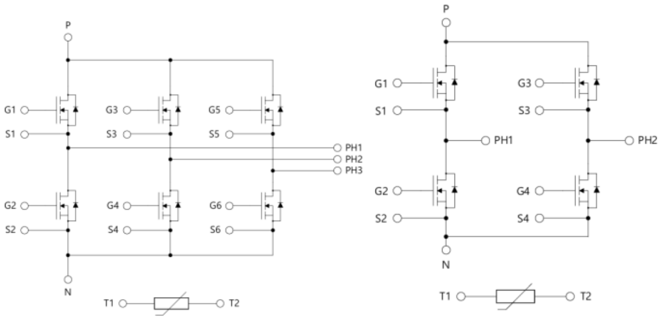
Target applications

- On-board Chargers (OBC)
- DC-DC Converter
- HV Thermal Management
- HVAC
- Industrial Drives
- EV-Charging
- PSU
- SMPS

Product collaterals / Online support

Product family page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
AMM12S18LB1ZXKMA1	SP006043202	PG-MDIP-32
AMM12S25LB1ZXKMA1	SP006043500	PG-MDIP-32
AMM12S36LB1ZXKMA1	SP006043512	PG-MDIP-32
AMM12S36LB1Z2XKMA1	SP006043506	PG-MDIP-32
AMM12S54LB1ZXKMA1	SP006043518	PG-MDIP-32
AMM12S54LB2ZXKMA1	SP006043524	PG-MDIP-32
AMM12S62LB1ZXKMA1	SP006043533	PG-MDIP-32
AMM12S62LB2ZXKMA1	SP006043552	PG-MDIP-32
AMF12S18LB2ZXKMA1	SP006061250	PG-MDIP-32
AMF12S25LB2ZXKMA1	SP006061254	PG-MDIP-32
AMF12S36LB2ZXKMA1	SP006061258	PG-MDIP-32
AMF12S54LB2ZXKMA1	SP006061262	PG-MDIP-32
AMF12S62LB2ZXKMA1	SP006061266	PG-MDIP-32

OPTIREG™ PMIC TLE9744QK Application Specific PMIC for traction inverter

The TLE9744QK is an application specific PMIC for traction inverter with integrated resolver exciter and a sophisticated safety engine (ISL) capable of putting the system in a safe state in case of a µC fail. The safe state is decided by evaluating signals on 6 analog, 5 digital inputs, watchdogs and µC supervision by the highly configurable integrated safety logic. Supports up to ASIL-D. Value proposition: BOM count, cost and space down.

Features

- Pre-regulator 1 and 2: for internal and external post-regulators
- Three LDOs and two tracker
- SPI interface
- Resolver excitation circuit
- Integrated Safety Logic (ISL)
- Phase current, DC-Link, gate driver status and MCU clock monitoring
- Torque control and DC-Link active discharge control
- Redundant supply input for ISL and tracker 2

Benefits

- Integrated inverter specific features
- Reduced BOM component count
- Reduced BOM cost
- Reduced BOM space
- Interoperable with Aurix™, EiceDRIVER™
- Developed according to ISO 26262, enabling systems up to ASIL D

Competitive advantage

- Traction inverter specific features enabling a lean, cost-efficient design

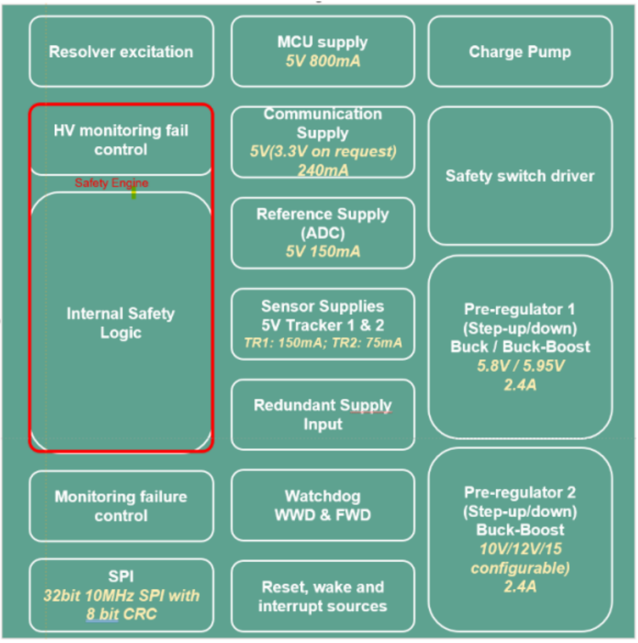
Target applications

- Traction inverter

Product collaterals / Online support

Product page

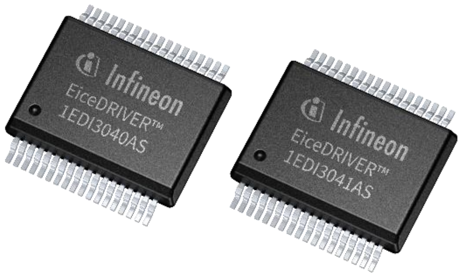
Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLE9744QKXUMA1	SP005343912	PG-LQFP-64

EiceDRIVER™ 1EDI304xAS isolated gate driver ICs for EV



EiceDRIVER™ 1EDI3040AS and 1EDI3041AS are automotive-qualified, 1200 V, single-channel gate driver ICs for IGBT and SiC traction inverters.

With reinforced isolation, ISO 26262 compliance (ASIL D), multi-level slew rate control and a runtime adjustable flyback controller (1EDI3040AS variant) these ICs offer a unique combination of features delivering unparalleled customer benefits.

To help customers get started quickly, Infineon provides a comprehensive suite of design support, including software and tools.

Features

- Made for IGBT and SiC MOSFETS
- Reinforced isolation with high CMTI >150 V/ns
- Multi-level slew rate control
- Closed loop integrated flyback controller (Error ≤±2%)
- Runtime VCC2 adjustability
- 6 channel isolated ADC
- DESAT and SOFTOFF incl. digital filtering for < 1us
- Power device state monitoring

Benefits

- Up to 35% inverter loss reduction over WLTP drive cycle
- Boost mode for deadtime reduction, saving inverter losses
- Integrated flyback controller saving external BOM
- Active V_{GS} control to optimized SiC device $R_{DS(ON)}$
- Compensated V_{GS} measurement for accurate $R_{DS(ON)}$
- Accurate $R_{DS(ON)}$ for lifetime monitoring and Tj estimation
- Fastest DESAT to maximize SiC utilization
- Saving system BOM via End-to-End safety mechanisms

Competitive advantage

- With reinforced isolation, ISO 26262 compliance (ASIL D), multi-level slew rate control and a runtime adjustable flyback controller (1EDI3040AS variant) these ICs offer a unique combination of features delivering unparalleled customer benefits

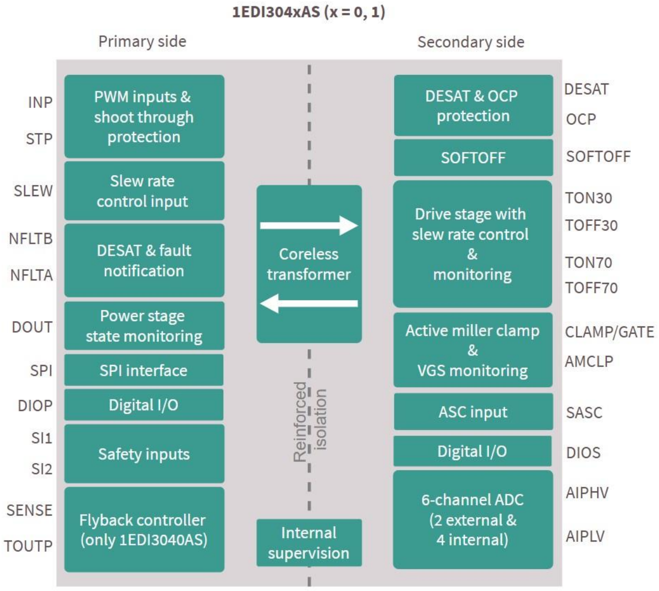
Target applications

- Traction inverter

Product collaterals / Online support

[Product page]

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
1EDI3040EVALBOARDTOBO1	SP006071958	L-MADK-1
1EDI3040EVALHPACKHDTOBO1	SP006185598	L-MADK-1
1EDI3040EVALIDPAKTOBO1	SP006185594	L-MADK-1
1EDI3040ASXUMA1	SP005910755	PG-LFDSO-36
1EDI3041ASXUMA1	SP005910759	PG-LFDSO-36

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FF2000R17T2P8 / FF1400R17T2P8 1700 V, 2000 A/1400 A half-bridge IGBT module in XHP™2 package

XHP™ 2 1700 V, 2000 A/1400 A half-bridge IGBT module with improved chipset IGBT8 and EC8, high power density and improved thermal management for more efficiency.

Features

- Low gate charge QG of IGBT 8 for improved paralleling
- Elevated softness of EmCon 8 for clean switching
- High performance ceramic for improved thermal cycling and highest performance
- Continuous operating temperatures at Tvj = 175°C

Benefits

- High power density
- Energy efficiency
- Improved thermal performance
- Low switching and conduction losses

Competitive advantage

- High power density
- Improved thermal performance
- More efficiency

Target applications

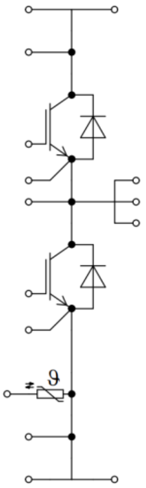
- Drives
- Photovoltaic
- Wind Power
- Energy storage
- Electrolysis
- Traction
- CAV

Product collaterals / Online support

Product page: FF2000R17T2P8BPSA1

Product page: FF1400R17T2P8BPSA1

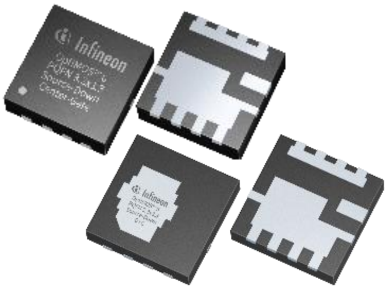
Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
FF2000R17T2P8BPSA1	SP006121939	AG-XHP2K17-831
FF1400R17T2P8BPSA1	SP006121934	AG-XHP2K17-831

OptiMOS™ 5 30 V and OptiMOS™ 6 40 V portfolio extension in Source-Down PQFN 3.3x3.3 with excellent price-performance ratio



The new OptiMOS™ 5 30 V and OptiMOS™ 6 40 V power MOSFET portfolio, in the industrial standard high performance PQFN 3.3x3.3 Source-Down Center-Gate, Bottom (BSC)- and Dual-Side (DSC) cooled packages, enables easy design-in on space-constrained PCB areas.
A best-price approach disrupts the status quo by delivering exceptional power density and a minimized form factor in end applications, enabling a compact design and optimizing the end user experience while offering best price-performance ratio.

Features

- Extended gate voltage rating
- 175°C temperature rating
- Same in class $R_{DS(on)}$ compared to competition
- Source-Down package with dual-side cooling variant
- Best price-performance

Benefits

- Fast switching of control MOSFET
- Low $R_{DS(on)}$ for Synch-Rec MOSFET
- Safe and reliable operation even at high MOSFET junction temperature
- Better FOMs and Miller ratio compared to competition
- Superior thermal capabilities
- Competitive price

Competitive advantage

- High performance products for cost sensitive applications
- Power loss mitigation enables system cost reduction and energy savings
- Strengthen the supply chain by providing an additional source to the market
- High performance package: industry standard – Source-Down PQFN 3.3x3.3 BSC / DSC
- MOSFET characteristics specifically tailored for applications in the low/medium power range

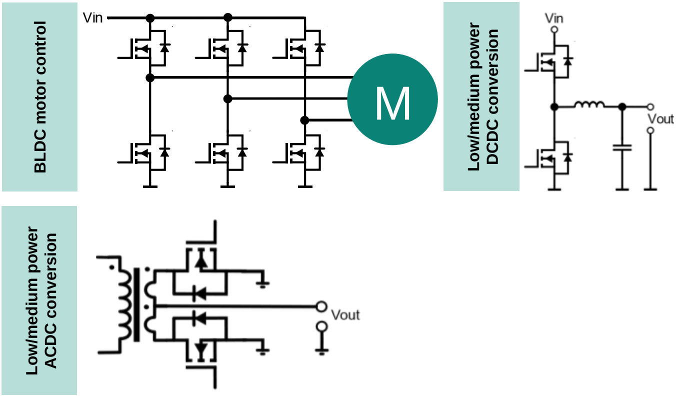
Target applications

- BLDC motor
- Brushed motor
- AUX Power
- BMS
- DC-DC
- AC-DC
- Low Power
- Medium Power

Product collaterals / Online support

Product family page

Block diagram



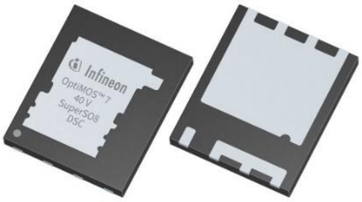
Product overview incl. datasheet link

OPN	SP Number	Package
IQE012N03LM5CGATMA1	SP006150052	PG-TTFN-9
IQE012N03LM5CGSCATMA1	SP006150056	PG-WHTFN-9
IQE020N04LM6CGATMA1	SP006150064	PG-TTFN-9
IQE020N04LM6CGSCATMA1	SP006150069	PG-WHTFN-9

Classification: Restricted document! The information presented is valid from May 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

OptiMOS™ 7 40 V motor-drives optimized power MOSFETs

Infineon's OptiMOS™ 7 40 V motor-drives optimized MOSFETs offer tailored solutions for efficient power conversion in drives, power and gardening tools. The portfolio extension expands the new 40 V family with additional products in the PQFN 5x6 dual-side cooled package for the highest thermal performance and optimized heat sink design.



Features

- Industry leading $R_{DS(on)}$
- Price-Performance optimized portfolio
- 3x wider SOA
- Short-circuit current limitation
- Higher threshold voltage Vth up to 3.2 V
- Controlled Transconductance gfs

Benefits

- Enhanced efficiency
- Improved robustness in harsh conditions
- Improved pulse current handling
- Immunity vs. short-circuit events
- Immunity vs. parasitic turn-on events
- Intrinsic short current limitation
- Improved slew rate control
- Better EMI behavior and ease of use

Competitive advantage

- With up to 20% reduced conduction loss, industry leading 0.5 mΩ $R_{DS(on)}$, and 3x wider SOA, the OptiMOS™ 7 motor-drives optimized ensures unmatched efficiency, reliability, and optimized price-performance for motor-drive applications. It offers up to 70% improved controllability, enhanced current sharing, and superior EMI performance. The new DSC variants offer optimized heat-sink design potentials for highest power dense solutions

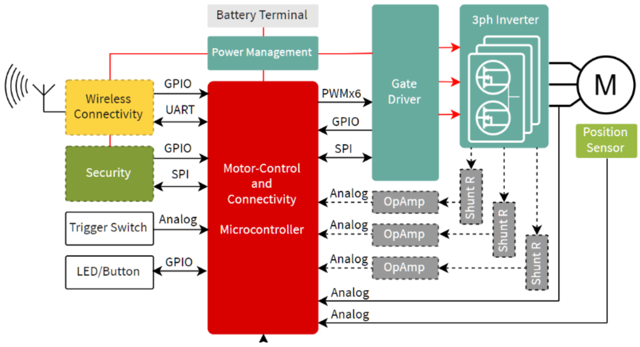
Target applications

- Power tools
- Cordless power tools and outdoor power equipment
- Cordless vacuum cleaners
- Non-stackable BMS solutions
- Low-power BDC/BLDC motor drive up to 72 V

Product collaterals / Online support

Product family page

Block diagram



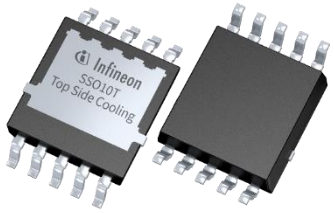
Product overview incl. datasheet link

OPN	SP Number	Package
ISCH57N04NM7VSCATMA1	SP006150609	PG-WSON-8
ISCH75N04NM7VSCATMA1	SP006150614	PG-WSON-8
ISCH92N04NM7VSCATMA1	SP006150616	PG-WSON-8

Classification: Restricted document! The information presented is valid from May 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

OptiMOS™ 80 V and 100 V top-side cooled SSO10T for 48 V motor drive, DC-DC converters and exterior LED lighting applications

Infineon expands its portfolio of automotive MOSFETs featuring the innovative, top-side cooled SSO10T 5x7mm^2 SMD package by introducing the market's first 100 V, as well as additional 80 V products. These products help customers achieve big advancements in cooling performance and power density in demanding automotive applications.



Features

- Direct cooling path to ECU housing
- Virtually no heat flows into PCB
- Industry's largest exposed pad area
- Freedom to route traces under package
- Can mount parts on back side of PCB
- Industry's best on-resistance, $R_{DS(on)}$
- Fast switching times (turn on/off)
- Tight threshold voltage, $V_{GS(th)}$, range

Benefits

- Enables excellent thermal management
- Thermal impedance improved 20% to 50%
- Helps reduce ECU volume or PCB area
- Helps reduce PCB cost (area, Cu, vias)
- Helps achieve highest power density
- Minimized conduction losses
- Superior switching performance
- Well-suited for parallel placement

Competitive advantage

- First to market with 100 V top-side cooled SSO10T MOSFETs
- The broadest portfolio of 80 V top-side cooled SSO10T MOSFETs to choose from
- Industry's best on-resistance, $R_{DS(on)}$
- Industry's largest exposed pad area
- Infineon automotive quality and reliability

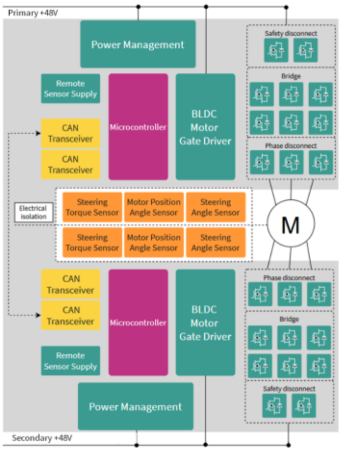
Target applications

- 48 V Electric Power Steering (EPS)
- 48 V Steer by Wire (SbW)
- HV-LV DC-DC converter
- 48 V-12 V DC-DC converter
- 48 V Pumps and Fans
- LED Headlamp Lighting
- ADAS/AD Domain Controller
- Zone Control Unit
- Humanoid Robots

Product collaterals / Online support

Product family page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
IAUCN08S7N016TATMA1	SP005981920	PG-LHDSO-10
IAUCN08S7N019TATMA1	SP005981924	PG-LHDSO-10
IAUCN08S7N024TATMA1	SP005981928	PG-LHDSO-10
IAUCN08S7N036TATMA1	SP006084578	PG-LHDSO-10
IAUCN08S7N045TATMA1	SP005911511	PG-LHDSO-10
IAUCN08S5L160TATMA1	SP006060865	PG-LHDSO-10
IAUCN10S7N025TATMA1	SP006063166	PG-LHDSO-10
IAUCN10S5L110TATMA1	SP006060852	PG-LHDSO-10
IAUCN10S7L290TATMA1	SP006060529	PG-LHDSO-10

OptiMOS™ 7 40 V in SSO4G 5x6 package

Infineon OptiMOS™ 7 40 V in SSO4G 5x6 leaded (PG-THSOG-4-1) focuses on Insulated Metallic Substrate and Legacy Leaded Footprint Design Compatibility.

The OptiMOS™ 7 40 V portfolio SSO4G 5x6 leaded package (PG-THSOG-4-1) ranges from 1.04 mOhm upto 4.70 mOhm.

Our broad portfolio of standard SSO8 5x6 (PG-TDSON-8) package is the best choice for performance and price for tomorrow’s automotive designs and applications and ranges from best in class 0.42 mOhm upto 4.30 mOhm.

Features

- 5x6 mm² footprint
- High current capability
- Available in leading-edge OptiMOS 7™ 40 V technology
- $R_{DS(on)}$ range: 1.0 mΩ – 4.7 mΩ
- Leaded package with Cu-Clip for IMS and legacy footprint design compatibility
- High avalanche capability and SOA ruggedness

Benefits

- Highest power and current density
- High thermal capacity lead-frame package
- Reduced conduction losses
- Optimized switching behavior
- High TCOB for IMS PCBs
- Legacy footprint design compatibility
- Automotive robust package

Competitive advantage

- Very good TCOB on IMS substrates
- 100% footprint compatibility for old designs

Target applications

- IMS Designs
- Legacy BLCD Footprint -Designs

Product collaterals / Online support

[Product family page]

Block diagram

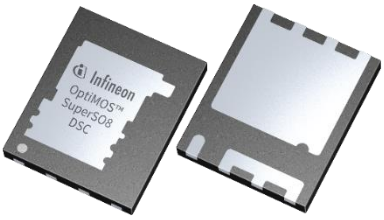
Standard automotive BLDC application

Product overview incl. datasheet link

OPN	SP Number	Package
IAUCN04S7N010GATMA1	SP005984384	PG-THSOG-4
IAUCN04S7N015GATMA1	SP005988884	PG-THSOG-4
IAUCN04S7N019GATMA1	SP005988880	PG-THSOG-4
IAUCN04S7N027GATMA1	SP005988868	PG-THSOG-4
IAUCN04S7N037GATMA1	SP005988864	PG-THSOG-4
IAUCN04S7N047GATMA1	SP005988860	PG-THSOG-4
IAUCN04S7L042GATMA1	SP006055284	PG-THSOG-4

OptiMOS™ 8 ISC019N10NM8SC n-channel power MOSFET 100 V in SuperSO8 DSC package with dual-side cooling (DSC)

OptiMOS™ 8 power MOSFET in SuperSO8 DSC (dual-side cooling) package offer all thermal management benefits of dual-side cooling solutions with an industry-standard footprint.



Features

- Industry's lowest $R_{DS(on)}$, high ID
- Reduced $V_{GS(th)}$ spread (< 1 V) and low transconductance (g_{fs})
- Excellent switching behavior and soft body diode
- Improved thermal performance
- Compatible with PQFN 5x6

Benefits

- Lowest conduction losses for high power density
- Optimal current sharing when paralleling MOSFETs
- Thermal robustness
- Ease of use

Competitive advantage

- Very low $R_{DS(on)}$
- Improved thermal performance
- High-efficiency MOSFET technology

Target applications

- Data center and AI data center solutions
- Telecommunications infrastructure
- Industrial and consumer BMS
- Server power supply units (PSU)

Product collaterals / Online support

Product page

Product overview incl. datasheet link

OPN	SP Number	Package
ISC019N10NM8SCATMA1	SP006181056	PG-WSON-8

Classification: Restricted document! The information presented is valid from May 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

EconoPACK™ 3 with IGBT7 for MV drives and motor control

The EconoPACK™ 3 1700 V TRENCHSTOP™ IGBT7 module delivers best-in-class performance for medium-voltage drive and motor control. Featuring emitter controlled 7 diode, integrated rectifier and NTC temperature sensor in an isolated base plate, it offers unmatched reliability and secured supply.

Features

- Low VCES (1700 V) with positive temperature coefficiency
- Isolated base plate
- RoHS compliant
- Established Econo module concept
- Solder contact technology
- Integrated NTC temperature sensor
- Integrated rectifier

Benefits

- High integration single module solution
- Low switching losses / lower junction temperature
- Increased power density
- Reducing cooling effort

Competitive advantage

- Easy to design products
- Best cost-performance ratio which leads to reduced system costs
- Enabling a strongly enhanced power density for a new generation of power modules

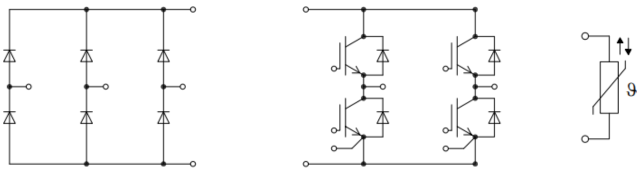
Target applications

- [Medium voltage (MV) drive]
- [Motor control]

Product collaterals / Online support

[Product page]

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
F475R17N3E7B58BPSA1	SP006031888	AG-ECONO3B-711

Classification: Restricted document! The information presented is valid from May 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

XENSIV™ TLI55950 amplified linear TMR position sensor

The XENSIV™ TLI55950 is an amplified linear position sensor featuring advanced TMR technology and an integrated operational amplifier. It delivers high-precision magnetic sensing with ultra-low noise and exceptional sensitivity. Compact and versatile, it ensures seamless integration into industrial and consumer applications, from power tools to robotics.

Features

> Linear position sensor in SOT23-6 package

> 5 V and 3.3 V supply voltage

> ±41/25 and ±25/16 mT magnet range

> Up to 85.5 mV/mT sensitivity

> Ultra-low noise (up to 8.1 µTRMS)

> JEDEC JESD47 product validation

Benefits

> High precision and sensitivity

> Compact and universal package

> Low power consumption

> Noise reduction for accurate readings

> Reliable performance across applications

> Cost-effective for high-sensitivity needs

Competitive advantage

> TMR-based magnetic sensing technology

> Integrated operational amplifier

> Wide magnetic range with full-scale output

> Temperature-compensated and pre-calibrated

> High noise immunity

> Versatile for industrial and consumer applications

Target applications

> Power tool trigger detection

> Service robots and drones angle sensing

> High precision dual encoder setups

> Low power applications

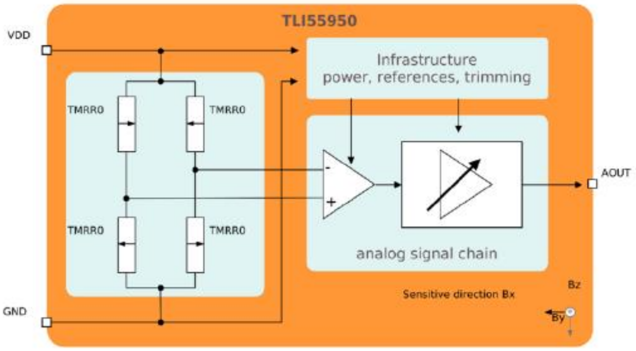
> Industrial automation

Product collaterals / Online support

[Product family page]

[Product page]

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLI55950A6EE0002XTSA1	SP006206460	PG-SOT23-6

Classification: Restricted document! The information presented is valid from May 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

XENSIV™ TLI55910 linear TMR position sensor

The XENSIV™ TLI55910 is a high-sensitivity and low-power linear position sensor that leverages tunnel magnetoresistance (TMR) technology to deliver precise linear measurements. This non-amplified analog sensor can measure magnetic fields with in a range of ±35 mT and boasts a large ratiometric output sensitivity of 5 mV/V/mT. This device is a versatile solution for various measurements such as displacement, linear, angle and rotary position sensing.

Features

- Linear position sensor with VortexTMR technology
- Magnetic measurement range: ±35 mT
- Ratiometric output sensitivity: 5 mV/V/mT
- Low noise: 5 µV RMS
- Ultra-low current consumption: 0.25 mA at 1.8 Vdd
- JEDEC JESD47 product validation
- Compact PG-SOT23-6-4 package

Benefits

- Precise and reliable measurements
- Ideal for battery-powered devices
- Enabling cost-effective magnet design
- Stable operation in harsh environments
- Robust against magnetic influences
- Versatile and enabling various sensing use cases

Competitive advantage

- Patented VortexTMR technology for high accuracy
- Low power consumption (0.25 mA at 1.8 Vdd)
- Wide magnetic measurement range (±35 mT)
- High ratiometric output sensitivity (5 mV/V/mT)
- Compact PG-SOT23-6-4 package for space efficiency

Target applications

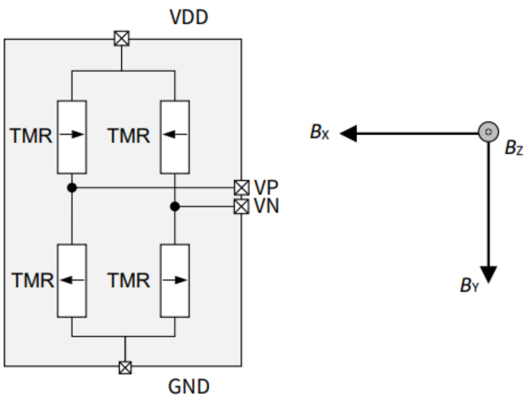
- Drones
- Industrial automation
- Home and building automation
- Robotics / robots systems

Product collaterals / Online support

[Product family page]()

[Product page]()

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLI55910A6EE0001XTSA1	SP006118939	PG-SOT23-6

EZ-PD™ CCG7S for automotive USB-C applications

Infineon launches new devices in the EZ-PD™ CCG7S family that integrates USB-C PD controller, Buck-Boost, and 4 switching FETs for automotive USB-C applications. The devices reduce the system BOM and optimize PCB footprint. With ARM® Cortex® M0 architecture with built-in flash, it complies with the latest PD3.2 standard and can meet OEM's customized requirements.

Features

- USB-PD, Buck-Boost, and 4 MOSFETs ($R_{DS(on)}$ TYP: 9 mΩ)
- Compliant to USB-PD v3.2
- ARM® Cortex®-M0, 16 KB SRAM, 128 KB Flash, 3x SCBs, 13 GPIOs
- Fault Protections and moisture detection
- Support LIN for diagnosis and communication
- Advanced software features like Blackbox and dynamic power sharing
- Compact 6.5 x 9.25 mm 40-LGA package
- Offer Software development kit

Benefits

- Highly integrated solution to reduce system BOM
- Programmability for custom system requirements
- Flexible Interfaces enable diagnosis on the USB-C module
- 65 W design without a heat sink and 100 W with a heat sink
- Fast time to market
- Support head unit, rear seat charger, and rear seat entertainment

Competitive advantage

- High integration with built-in high-performance switching MOSFETs
- Reduces BOM cost while delivering excellent thermal performance and efficiency
- Built-in flash + ARM® Cortex®-M0 for flexible system customization

Target applications

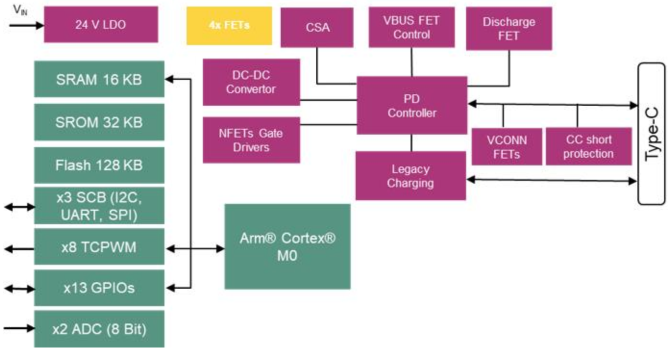
- Head unit (HU) charger
- Rear seat charger (RSC)
- Rear seat entertainment (RSE)

Product collaterals / Online support

Product family page

Block diagram

Sync buck:



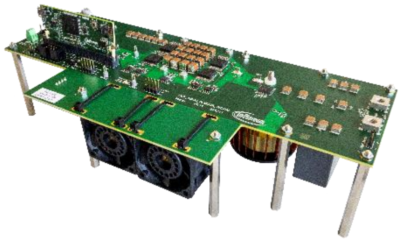
Product overview incl. datasheet link

OPN	SP Number	Package
CYPD719440BFXSXQLA1	SP006142927	PG-TFLGA-40
CYPD719440BFXSTXUMA1	SP006142929	PG-TFLGA-40
CYPD719540BFXSXQLA1	SP006142937	PG-TFLGA-40
CYPD719540BFXSTXUMA1	SP006142939	PG-TFLGA-40
CYPD719640BFXSXQLA1	SP006142956	PG-TFLGA-40
CYPD719640BFXSTXUMA1	SP006142958	PG-TFLGA-40

Classification: Restricted document! The information presented is valid from May 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

REF_10KW_3LBUCK_SiC400 3-level flying capacitor buck with CoolSiC™ MOSFET 400 V G2

The reference board REF_10KW_3LBUCK_SIC400 uses a 3-level-flying capacitor Buck DC/DC converter, which can also be reconfigured to be used as a 2-level Buck DC/DC converter. The primary goal of the platform is to enable evaluation of CoolSiC™ MOSFET 400 V and 650 V G2 in TOLL and D2PAK-7 packages. The reference design also aims to provide layout guidelines to optimize the commutation and gate loops and provide solutions for auxiliary supply for floating gate-drive, startup, pre-charging and voltage balancing of the flying capacitor in multi-level topologies. By enabling a fair benchmarking between 3-level (3L) and 2-level (2L) topologies, the benefits of a 3-level topology can be evaluated.



Features

- Evaluate CoolSiC™ MOSFET 400 V/650 V G2 MOSFETs
- Compare 3-level vs 2-level topologies
- Flying capacitor balancing algorithm
- Compact and low-cost planar transformer gate supply
- Test bipolar vs unipolar gate drive
- Adjustable gate-drive voltage
- Supports Kelvin and Power-Source gate drive reference
- Low inductance high-power PCB design
- Heatsink-based air cooling system

Benefits

- Lower inductor voltage swing (-50%)
- Ripple frequency double of MOSFET switching frequency
- Inductance value reduced by 75%
- Inductor optimized for higher efficiency
- Smaller inductor boosts power density
- Lower MOSFET blocking voltage
- Significantly reduced switching losses

Competitive advantage

- Platform to evaluate CoolSiC™ MOSFET 400 V / 650 V G2, benchmarking 3L vs 2L topologies by shorting outer leg MOSFETs QHSO and QLSO for 2L operation
- Flying capacitor balancing algorithm
- Low-cost and low-space discrete planar-transformer based isolated auxiliary gate drive supply for 4 x HF leg MOSFETs
- Support for testing bipolar vs. unipolar gate drive with adjustable driving voltage
- Selectable gate drive with respect to Kelvin-Source (KS 4-terminal drive) or Power-Source (PS 3-terminal drive)
- Low commutation and gate-loop inductance in a high-power design with a heatsink for cooling

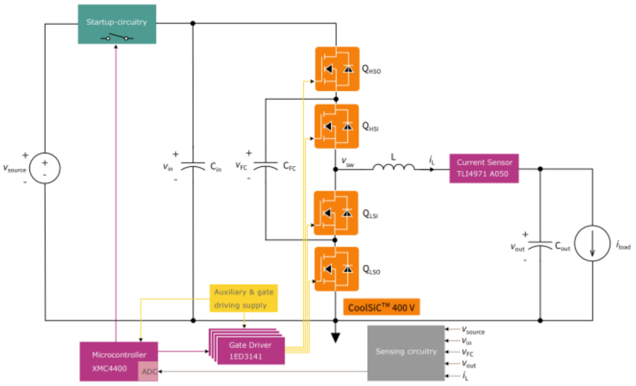
Target applications

- Power Back-up Units (BBUs, CBUs)
- Server PSUs
- Photovoltaic
- Batter energy storage (BESS)
- Motor control
- Uninterruptible power supplies (UPS)

Product collaterals / Online support

Board page

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
REF10KW3LBUCKSIC400TOBO1	SP006135438	L-MADK-1

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